

Updated on June, 18, 2018

“IMS 2018” had finished successfully. Thank you for visiting the booth of A.L.M.T. Corp.

A.L.M.T. Corp. will participate in IMS2018, scheduled from 12-14, June, 2018.

This exhibition is International Microwave symposium.

There we will exhibit mainly heatspreaders, including Ag-Diamond, CPC.

IMS 2018

- Dates : 12-14, June, 2018
- Venue : Pennsylvania Convention Center Philadelphia, Pennsylvania
- Stand : Booth, 2153, A.L.M.T.Corp.

Floor Maps: <https://www.expodweb.com/18ims/ec/forms/attendee/indexTab.aspx>

Main Exhibits; Heatspreaders

Ag-Diamond

Characteristics: High Thermal Conductivity, more than 600 W/mK. Low Co-Efficient Thermal Expansion, less than Pure Copper. High Thermal Resistance, it can be worked normal silver-brazing at 800°C.

Applications: High Performance Ceramics Package, Heatspreader for SiC/GaN High Powered Device

CPC

Characteristics: CPC is a composite material with a laminated structure with Cu layers above and below the Cu-Mo composite material. Thermal conductivity and linear expansion coefficient can be changed by combining the composition of the core material Cu-Mo and the lamination ratio. In addition, because both surfaces are Cu, the initial heat radiation effect is excellent.

Applications: Amplifier substrates of mobile phone base stations.

For further detailed information about the exhibition, please refer to <https://www.ims2018.org/>



**The 2018 IEEE MTT-S
International Microwave Symposium**
10-15 June 2018 Philadelphia, PA